

INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Not for submission under 37 CFR 1.99)	Application Number		10644718
	Filing Date		2003-08-20
	First Named Inventor	Yi-Hsun Wu et al.	
	Art Unit	2836	
	Examiner Name	Danny Nguyen	
	Attorney Docket Number	TSMC2003-246/1085-191	

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1	JIAN-HSING LEE, J.R. SHIH, Y.H. WU, T.C. ONG, "The Failure Mechanism Of High Voltage Tolerance IO Buffer Under ESD," IEEE 03CH37400. 41st Annual International Reliability Physics Symposium, Dallas, Texas, 2003 (Pages 269-276) © 2003 IEEE.	<input type="checkbox"/>
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